

Proposed Set of PMDs, Related Specifications and Rationale

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May 23-25, 2000
IEEE 802.3ae Interim Meeting, Ottawa

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Objective

- To propose a set of PMD implementations that
 - meet all the P802.3ae distance objectives and criteria
 - provide an optimal mix of technologies
- The set consists of
 - Serial 850 nm
 - 850 nm CWDM proposed by Wiedemann, 5/00
 - 3-PMD set proposed by Hanson, 5/00: 1300 WWDM, 1310 Serial, 1550 Serial
- Target 850 nm Serial specifications are described
- Rationale on PMD optimization

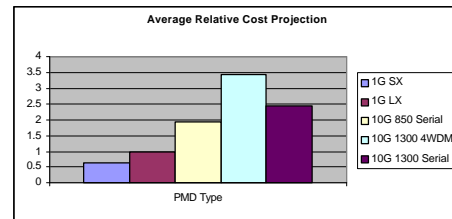
Critical Optimization Dimensions

- Cost
- Risk
 - Manufacturability
 - Time to Market
 - Market Acceptance
- Application Space Coverage
- Implementation Complexity
- Proven Technical Feasibility
- Multi-vendor support

Cost Optimization

- Must have low cost solution for short reach application
 - Most cost sensitive application space
 - The highest volume application space
 - 90% of 10GbE ports expected to be in enterprise
 - Source: Technical Essence Webs
- 92% of enterprise backbones <300 meters
- The 300 meter objective must be served with the lowest cost PMD for broad market acceptance
 - Historically SX technology is lowest cost
 - 80 - 90% of GbE market is SX (lowest cost and <300 m coverage)

Cost Projections from Reflector



| PMD Type | Rich T. | Jack J. | Paul K. | Ed C. | Ave. |
|---------------------------------|---------|---------|---------|-------|------|
| 1 GbE SX PHY current cost | - | 0.5 | 0.67 | 0.7 | 0.62 |
| 1 GbE LX PHY current cost | 1 | 1.00 | 1.00 | 1 | 1.00 |
| 10 GbE Serial 850 nm in (2002) | 2-3 | 1.25 | 1.50 | 2.5 | 1.94 |
| 10 GbE WWDM 1300 nm in (2002) | 3-4 | 4.00 | 2.92 | 3.3 | 3.43 |
| 10 GbE Serial 1300 nm in (2002) | 2-4 | 2.00 | 2.25 | 2.6 | 2.46 |

850 Serial projected to have the lowest cost.
850 CWDM cost claims competitive with 850 Serial.



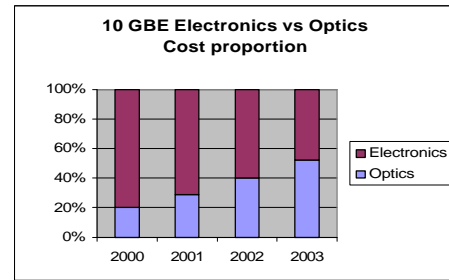
Intrinsic Cost Driver Comparison

| Cost element | 4λ WDM | 850 Serial |
|--------------------|--|--------------|
| Lasers & drivers | 4 (λ-selected) | 1 |
| Detectors & amps | 4 | 1 |
| Optical alignments | 10 SM/MM (5 Tx & 5 Rx) Offset Patch Cord | 2 MM |
| Optical filters | 4 or 8 | 0 |
| Mux | 1 optical | 1 electrical |
| Demux | 1 optical | 1 electrical |
| IC speed | 3.1 G | 10.3 G |

IC costs decline much faster than optics costs.
Optics costs drive total costs over time.

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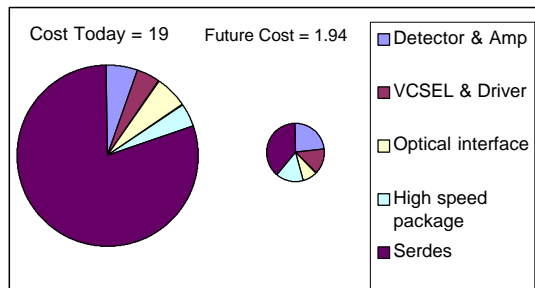
Optics cost drives total cost over time



Cost Reduction
 Electronics 50%/year
 Optics 18%/year

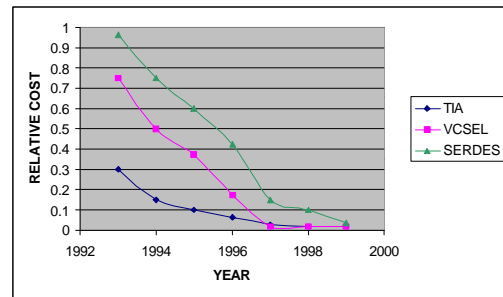
Drivers
 Moore's law, SiGe, CMOS
 Packaging improvements,
 materials cost reductions_s

SX Relative Costs: 10G / 1G



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IC Cost Trends For 1G

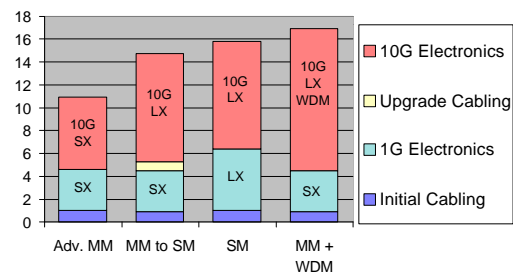


ICs decline by factors of 20 to 30.
 Average selling price of 1G SerDes Chip in 1999 is
 about the price of 2 beers per Dataquest.
 These chips were several hundreds of dollars initially.

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System Upgrade Cost Comparison

1 GbE Riser + Upgrade Riser to 10 GbE



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Risk Minimization

- **Manufacturability**
 - Introduction of new technologies can lead to unforeseen delays
 - Recent examples: Parallel Solutions and SFF Transceivers at 1G
 - 850 nm serial solutions are a direct evolution of existing technologies
- **Time to Market**
 - Lower risk technologies lead to faster time to market
 - Many IC and serial PMD vendors developing serial products
- **Market Acceptance**
 - End-users historically accept new media that provides new application coverage while retaining support for legacy systems
 - New MMF demand following same trend

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Market Acceptance

- Customers already have installed next generation MMF
- Lucent's LazrSPEED™ MMF available since January**
- Sample installations to date:**

Agilent
 BMW
 Merrill Lynch
 Nokia
 Peco Genco
 Pike's Peak College
 University of Texas
 Wells Fargo

Demand exceeding projections.

**Other manufacturers to supply new MMF include:
 Alcatel, Corning and Plasma**

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Market Acceptance

- Some reasons why customers install new MMF
 - End users believe that serial 850 will likely end up providing the lowest system cost.
 - The fact that cabling is a small part of the overall system cost today, and a decreasing fraction as speeds increase.
 - End users desire to manage legacy, current, and future applications on one fiber type. (SM is NOT backward compatible to the <1Gbs applications that most end users must support)
 - Aversion of end-users to installing difficult to terminate single mode fiber in buildings.
 - The relative ease with which building backbones can be upgraded.

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Market Acceptance

- Sufficient PMD offering critical
 - Additional PMDs do not retard market
 - 100BASE-T2 / T4 / TX example:
 - T2 and T4 targeted installed Cat 3 UTP
 - TX targeted new Cat 5 at lower cost
 - Only TX was accepted by market
 - Cat 5 rapidly displaced Cat 3 in more difficult to upgrade horizontals
 - What would have happened to Ethernet without TX and Cat 5 UTP?
 - Offering sub-optimal solutions retards market
 - Example: A Humvee is an all-purpose vehicle, but unacceptable as one-size fits all solution
 - Market acceptance depends on how well we match solution to customer needs

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Application Space Coverage

- Must have cost-optimized solution for short reach market
 - 850 nm Serial is optimized for 300 m application space
- Customers need sub-100m solutions
 - 10G application heavily used in equipment room.
 - While no survey of equipment room link lengths available, < 100 m capability sufficient for equipment clusters, so can reuse existing fiber with serial 850 nm solution.
 - Equipment room cabling is often point to point jumpers.
 - Cost of jumpers dwarfed by cost of new electronics.
 - New MMF can easily be deployed in equipment room for longer lengths.

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Implementation Complexity

- Serial Optics less complex than WDM optics
- Serial approach requires more complex Integrated Circuits
 - Many IC vendors addressing design issues
 - Cost savings result from technology advancements (SiGe, CMOS), volumes and competition
- Optical complexity includes difficult to reduce overheads
 - alignment tolerances
 - parts count
 - hybrid assembly techniques
 - mode-conditioning patch cords for SMF optics on MMF
- Favorable to trade optical complexity for IC complexity

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Proven Technical Feasibility

- Serial 850 nm technology repeatedly demonstrated feasible by multiple PMD and fiber vendors.
- Operational under worse-than-worst-case stress conditions
- Fiber bandwidth test method and laser launch conditions in fast-track development in TIA FO-2.2 aligned with IEEE schedule
 - Benefiting from 1G experience
 - System proposal in place, backed by powerful simulation capability
 - Participants include
 Agilent, Alcatel, Cielo, Compaq, Corning, GN Nettest, IBM, Infineon, Lucent, Naval SWC, NIST, Nortel, Picolight, Plasma, Raytheon, Siecor
- Cabling standards agree to add new MMF specifications
 - See TR42 Liaison Letter to IEEE 802.3 and 802.3ae of May 19, 2000

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Technical Feasibility / Multi-Vendor Support

- Technical demonstrations performed by multiple companies

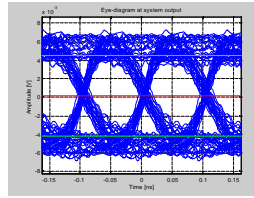
| VCSEL / Fiber | Rate | Distance | Comments |
|---------------------|-----------|----------|------------------------------------|
| Lucent | 10 Gb/s | 2800m | $<10^{-12}$ BER |
| Lucent | 10 Gb/s | 300m | $<10^{-12}$ BER, beyond worst case |
| Gore / Corning | 10 Gb/s | 600m | |
| Gore / Lucent | 10 Gb/s | 900m | $<10^{-12}$ BER |
| Cielo / Lucent | 12.5 Gb/s | 300m | $<10^{-14}$ BER |
| Picolight / Lucent | 10 Gb/s | 400m | $<10^{-12}$ BER |
| Gore / Alcatel | 10 Gb/s | 300m | |
| IBM / Gore / Lucent | 10 Gb/s | 500m | Robustness tested |
| New Focus / Lucent | 10 Gb/s | 300m | $<10^{-13}$ BER |
| Picolight / Corning | 10 Gb/s | 300m | |

Ensures competition in market

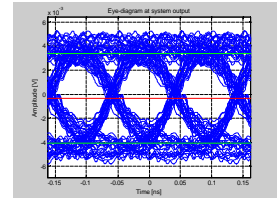
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Technical Feasibility - IBM Data

Back-to-back



300 m LazrSPEED™



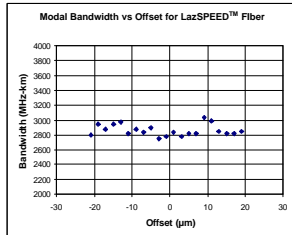
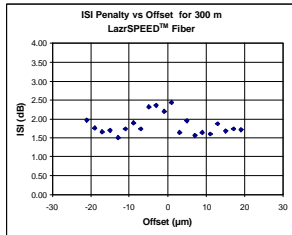
IBM



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Bell Labs Innovations

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Technical Feasibility - IBM Data



IBM



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Figure 38-1

- Almost the same as in 802.3z
- The mode conditioning patch cord does **not** apply

(802.3z Figure 38-1 shows PMA, PMD, Fiber Optic Cabling (channel) and four test points)

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Table 38-2

Operating range for 10000BASE-SX over each optical fiber type

| Fiber type | Modal BW @ 850 nm (min. overfilled launch except as noted) (MHz*km) | Minimum range (meters) |
|-------------|---|------------------------|
| 50 μm MMF | 2000 ^a | 2 to 300 |
| 50 μm MMF | 500 | 2 to 86 |
| 50 μm MMF | 400 | 2 to 69 |
| 62.5 μm MMF | 200 | 2 to 35 |
| 62.5 μm MMF | 160 | 2 to 28 |
| 10 μm SMF | N/A | Not Supported |

a. Bandwidth and launch condition details being defined by TIA FO2.2.

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Table 38-3

10000BASE-SX transmitter characteristics

| Description | 50 μm MMF | 62.5 μm MMF | Unit |
|--|---------------------|-------------|-------|
| Transmitter Type | Shortwave Laser | | |
| Signaling speed | 10.3125 +/- 100 ppm | | Gbd |
| Wavelength (λ, range) | 840 to 860 | | nm |
| Trise/Tfall (max; 20%-80%) | 31.5 | | ps |
| RMS spectral width (max) ^a | 0.35 | | nm |
| Average launch power (max) | See note b. | | dBm |
| Average launch power (min) | -5.5 | | dBm |
| Average launch power of OFF transmitter (max) | -30 | | dBm |
| Extinction ratio (min) ^c | 6.5 | | dB |
| RIN (max) | -125 | | dB/Hz |
| Encircled flux @ r = 15 μm in 50 μm fiber (min) ^d | 85 | | % |

- Experimental evidence suggests larger values are supportable.
- The lesser of class 1 safety limit or average receive power (max).
- A change to Optical Modulation Amplitude (OMA) is proposed.
- Measured per TIA/EIA 455-203 (draft). Subject to relaxation.

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Table 38-4

1000BASE-SX receiver characteristics

| Description | 50 μm MMF | 62.5 μm MMF | Unit |
|--|---------------------|-------------|------|
| Signaling Speed (range) | 10.3125 +/- 100 ppm | | GBd |
| Wavelength (range) | 840 to 860 | | nm |
| Average receive power (max) | -1.0 | | dBm |
| Receive sensitivity | -13.0 | | dBm |
| Return loss (min) | 12 | | dB |
| Stressed receive sensitivity | -8.5 | -7.6 | dBm |
| Vertical eye closure penalty | 2.5 | 3.0 | dB |
| Receive electrical 3 dB upper cutoff frequency (max) | 12.3 | | GHz |

Table 38-5

Worst case 1000BASE-SX link power budget and penalties

| Parameter | 50 μm MMF | | | 62.5 μm MMF | | Units |
|--|-------------------|------|------|-------------|------|--------|
| | 2000 ^a | 500 | 400 | 200 | 160 | |
| Modal BW @ 850 nm (min. overfilled launch except as noted) | | | | | | MHz-km |
| Link Power budget | 7.5 | 7.5 | 7.5 | 7.5 | 7.5 | dB |
| Operating Distance | 300 | 86 | 69 | 35 | 28 | m |
| Channel insertion loss | 2.59 | 1.81 | 1.75 | 1.63 | 1.60 | dB |
| Link power penalties | 4.68 | 4.89 | 4.89 | 4.83 | 4.83 | dB |
| Unallocated margin | 0.23 | 0.80 | 0.86 | 1.04 | 1.07 | dB |

a. Bandwidth and launch condition details being defined by TIA FO2.2.

Table 38-10

1000BASE-SX link jitter budget

| Compliance point | Total jitter | | Deterministic jitter | |
|------------------|--------------|------|----------------------|------|
| | UI | ps | UI | ps |
| TP1 | 0.24 | 23.3 | 0.100 | 9.7 |
| TP1 to TP2 | 0.284 | 27.5 | 0.100 | 9.7 |
| TP2 | 0.431 | 41.8 | 0.200 | 19.4 |
| TP2 to TP3 | 0.170 | 16.5 | 0.050 | 4.8 |
| TP3 | 0.510 | 49.5 | 0.250 | 24.2 |
| TP3 to TP4 | 0.332 | 32.2 | 0.212 | 20.6 |
| TP4 | 0.749 | 72.6 | 0.462 | 44.8 |

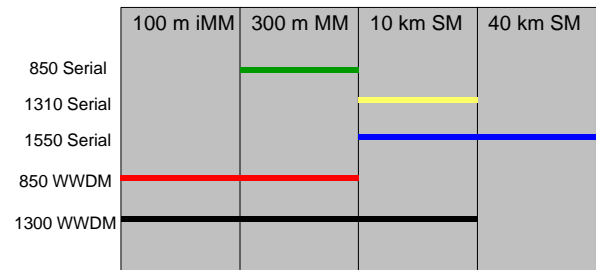
Notes and Further Work

- Notes
 - Used Piers Dawe's link model (version 041) with the following adjustments: MPN k factor = 0.5, baud rate for MPN beta, DCD_DJ = 9.7 ps except for New MMF DCD_DJ = 8.0 ps.
- Further Work
 - Target specifications at least 60% complete. Refinement work underway.

Summary

- Broad Market Potential / Application Space Coverage
 - Bulk of market is short reach. 10GbE must provide solution optimized for the <300 m application space.
- Economic Feasibility
 - 850-nm serial will be the lowest cost. As IC costs decline, cost determined by intrinsic optics complexity.
- Technical Feasibility
 - Serial 850 nm demonstrated more than any other emerging technology. Target specifications realistic. Direct evolution of existing technology provides low risk path.
- Multi-Vendor Support and Supply
 - Many companies supporting 850 nm serial technology. Ensures competition and product availability.

Coverage of Top 5-PMD Set



The fastest route to consensus